

2SJ576

Silicon P Channel MOS FET
High Speed Switching

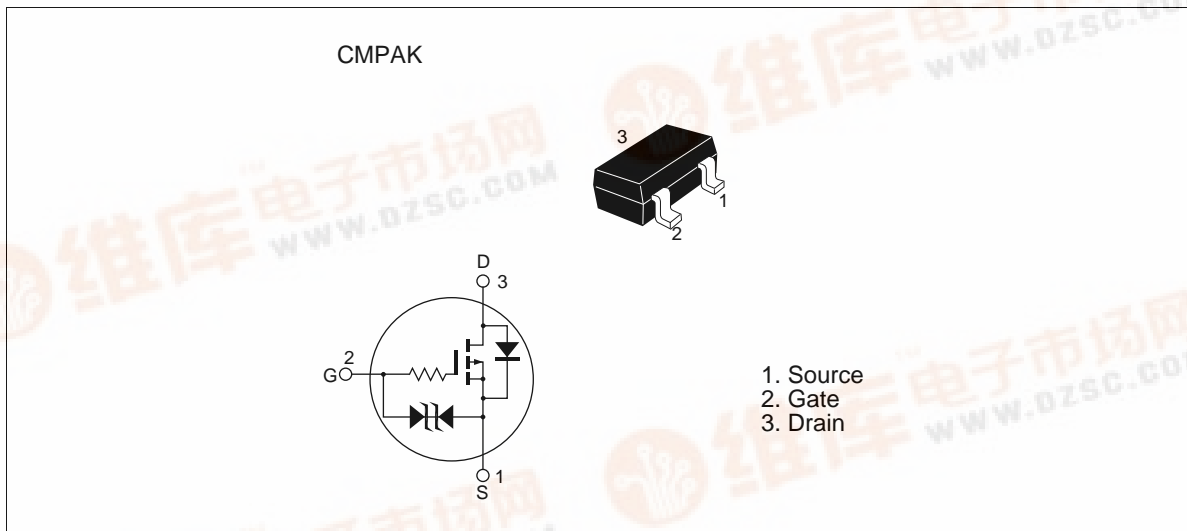
HITACHI

ADE-208-741B (Z)
3rd.Edition.
June 1999

Features

- Low on-resistance
 $R_{DS} = 2.8 \Omega$ typ. ($V_{GS} = -10 V$, $I_D = -50 mA$)
 $R_{DS} = 5.7 \Omega$ typ. ($V_{GS} = -4 V$, $I_D = -50 mA$)
- 4 V gate drive device.
- Small package (CMPAK)

Outline



2SJ576

Absolute Maximum Ratings (Ta = 25°C)

| Item | Symbol | Ratings | Unit |
|--|----------------------------------|-------------|------|
| Drain to source voltage | V_{DSS} | -30 | V |
| Gate to source voltage | V_{GSS} | ±20 | V |
| Drain current | I_D | -100 | mA |
| Drain peak current | $I_{D(pulse)}$ ^{Note 1} | -400 | mA |
| Body-drain diode reverse drain current | I_{DR} | -100 | mA |
| Channel dissipation | Pch ^{Note 2} | 300 | mW |
| Channel temperature | Tch | 150 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |

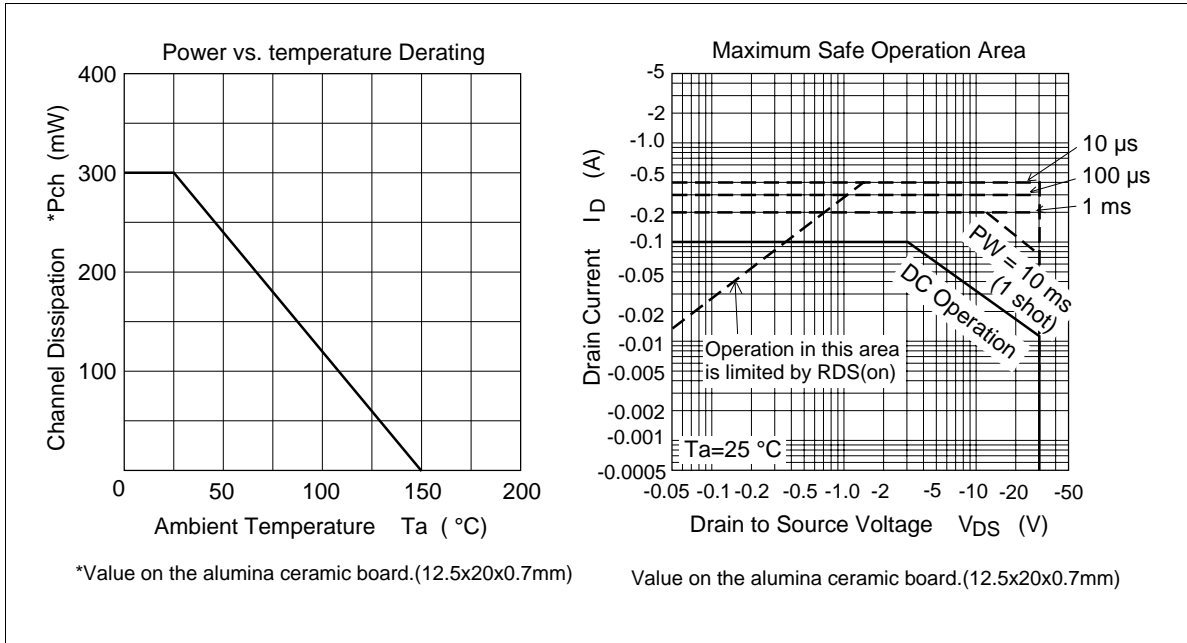
Note: 1. PW ≤ 10 μs, duty cycle ≤ 1%
 2. Value on the alumina ceramic board (12.5x20x0.7 mm)

Electrical Characteristics (Ta = 25°C)

| Item | Symbol | Min | Typ | Max | Unit | Test Conditions |
|--|---------------|------|-----|------|------|--|
| Drain to source breakdown voltage | $V_{(BR)DSS}$ | -30 | — | — | V | $I_D = -100 \mu A, V_{GS} = 0$ |
| Gate to source breakdown voltage | $V_{(BR)GSS}$ | ±20 | — | — | V | $I_G = \pm 100 \mu A, V_{DS} = 0$ |
| Gate to source leak current | I_{GSS} | — | — | ±5 | μA | $V_{GS} = \pm 16 V, V_{DS} = 0$ |
| Zero gate voltage drain current | I_{DSS} | — | — | -1 | μA | $V_{DS} = -30 V, V_{GS} = 0$ |
| Gate to source cutoff voltage | $V_{GS(off)}$ | -1.3 | — | -2.3 | V | $I_D = -10 \mu A, V_{DS} = -5 V$ |
| Static drain to source on state resistance | $R_{DS(on)}$ | — | 2.8 | 3.3 | Ω | $I_D = -50 mA, V_{GS} = -10 V$ ^{Note 3} |
| | $R_{DS(on)}$ | — | 5.7 | 7.9 | Ω | $I_D = -50 mA, V_{GS} = -4 V$ ^{Note 3} |
| Forward transfer admittance | $ y_{fs} $ | 68 | 105 | — | mS | $I_D = -50 mA, V_{DS} = -10 V$ ^{Note 3} |
| Input capacitance | Ciss | — | 25 | — | pF | $V_{DS} = -10 V$ |
| Output capacitance | Coss | — | 20 | — | pF | $V_{GS} = 0$ |
| Reverse transfer capacitance | Crss | — | 8 | — | pF | f = 1 MHz |
| Turn-on delay time | $t_{d(on)}$ | — | 10 | — | ns | $I_D = -50 mA, V_{GS} = -10 V$ |
| Rise time | t_r | — | 15 | — | ns | $R_L = 200 \Omega$ |
| Turn-off delay time | $t_{d(off)}$ | — | 40 | — | ns | |
| Fall time | t_f | — | 45 | — | ns | |

Note: 3. Pulse test
 4. Marking is AP
 See characteristics curves of 2SJ575

Main Characteristics



Cautions

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